

ESD Protection Diode

Low Clamping Voltage

PACDN042

Product Description

The PACDN042/43/44/45/46 family of surge protection arrays provide a very high level of protection for sensitive electronic components that may be subjected to electrostatic discharge (ESD). The PACDN042/43/44/45/46 devices safely dissipate ESD strikes, exceeding the IEC 61000-4-2 International Standard, Level 4 (±8 kV contact discharge). All pins are rated to withstand ±20 kV ESD pulses using the IEC 61000-4-2 contact discharge method. Using the MIL-STD-883D (Method 3015) specification for Human Body Model (HBM) ESD, all pins are protected from contact discharges of greater than ±30 kV.

Features

- Two, Three, Four, Five, or Six Surge Protection
- Compact SMT Package Saves Board Space and Facilitates Layout in Space-Critical Applications
- In-System ESD Protection to ±20 kV Contact Discharge, per the IEC 61000-4-2 International Standard
- These Devices are Pb-Free and are RoHS Compliant

Applications

- ESD Protection of PC Ports, Including USB Ports, Serial Ports, Parallel Ports, IEEE1394 Ports, Docking Ports, Proprietary Ports,
- Protection of Interface Ports or IC Pins which are Exposed to High **ESD** Levels







SOT-23-6 CASE 527AH CASE 527AJ





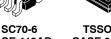


CASE 527AF CASE 419AB

CASE 419AC











TSSOP8 CASE 419AD CASE 948AL

CASE 846AB

MARKING DIAGRAM



XXX = Specific Device Code

Μ = Date Code = Pb-Free Package

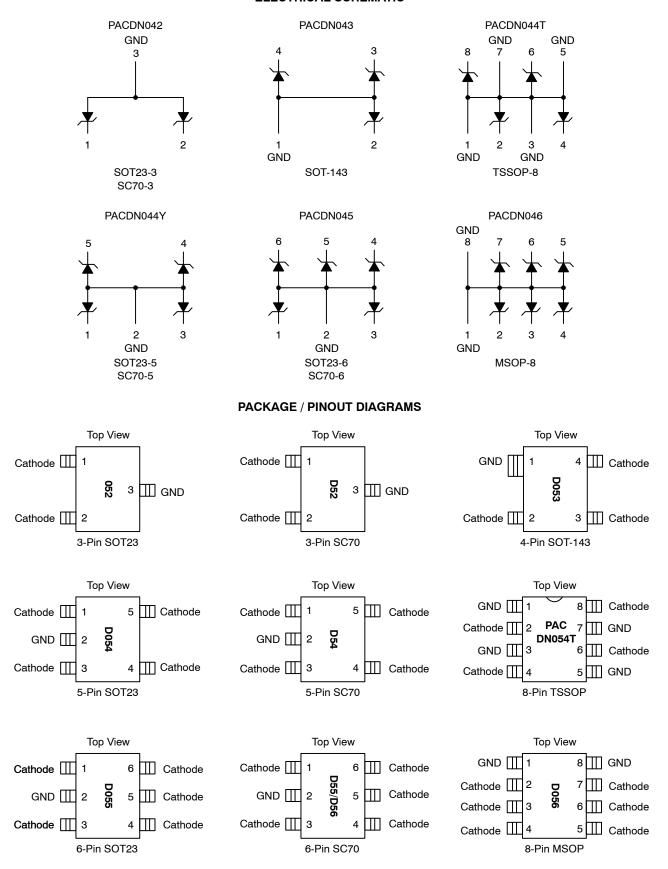
(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information on page 5 of this data sheet.

NOTE: Some of the devices on this data sheet have been **DISCONTINUED**. Please refer to the table on page 5.

ELECTRICAL SCHEMATIC



Note: SOT23, SC70, SOT-143, TSSOP, and MSOP Packages may differ in size. These drawings are not to scale.

Table 1. PIN DESCRIPTIONS

Pins	Name	Description
(Refer to Package Outline Drawings)	Cathode	The cathode of the respective surge protection diode, which should be connected to the node requiring transient voltage protection.
(Refer to Package Outline Drawings)	GND	The anode of the surge protection diodes.

SPECIFICATIONS

Table 2. ABSOLUTE MAXIMUM RATINGS

Parameter	Rating	Unit
Storage Temperature Range	-65 to +150	°C
Package Power Dissipation SC70 SOT23-3, SOT23-5, SOT23-6, SOT-143 TSSOP, MSOP	0.2 0.225 0.5	W

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 3. STANDARD OPERATING CONDITIONS

Parameter	Rating	Unit
Operating Temperature	-40 to +85	°C

Table 4. ELECTRICAL OPERATING CHARACTERISTICS

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
С	Capacitance	T _A = 25 °C, 2.5 VDC, 1 MHz		30		pF
V _{RSO}	Reverse Stand-off Voltage	I _R = 10 μA, T _A = 25 °C	5.5			V
		I _R = 1 mA, T _A = 25 °C	6.1			V
I _{LEAK}	Leakage Current	V _{IN} = 5.0 VDC, T _A = 25 °C		1	100	nA
V _{SIG}	Small Signal Clamp Voltage Positive Clamp Negative Clamp	I = 10 mA, T _A = 25 °C I = -10 mA, T _A = 25 °C	6.2 -0.4	6.8 -0.8	8 -1.2	V
V _{ESD}	ESD Withstand Voltage Human Body Model, MIL-STD-883, Method 3015 Contact Discharge per IEC 61000-4-2 Standard	(Note 1) (Note 1)	±30 ±20			kV
R _D	Diode Dynamic Resistance Forward Conduction Reverse Conduction			1.0 1.4		Ω

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

^{1.} ESD voltage applied between channel pins & ground, one pin at a time; all other channel pins open; all GND pins grounded.

PERFORMANCE INFORMATION

Diode Capacitance

Typical diode capacitance with respect to positive cathode voltage (reverse voltage across the diode) is given in Diode Capacitance vs. Reverse Voltage.

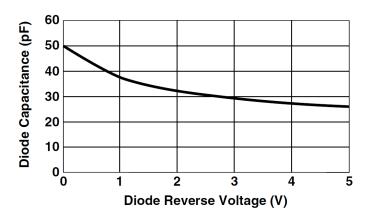


Figure 1. Diode Capacitance vs. Reverse Voltage

Typical High Current Diode Characteristics

Measurements are made in pulse mode with a nominal pulse width of 0.7 mS.

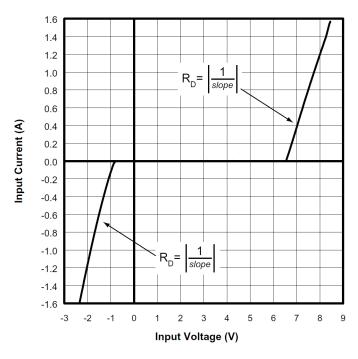


Figure 2. Typical Input VI Characteristics (Pulse-mode measurements, pulse width = 0.7 mS nominal)

ORDERING INFORMATION

Device	Package	Shipping [†]
PACDN042Y3R	SOT23-3 (Pb-Free)	3000 / Tape & Reel
PACDN045YB6R-R	SC70-6 (Pb-Free)	3000 / Tape & Reel

DISCONTINUED (Note 2)

PACDN044Y5R	SOT23-5 (Pb-Free)	3000 / Tape & Reel
PACDN045Y6R	SOT23-6 (Pb-Free)	3000 / Tape & Reel
PACDN043Y4R	SOT-143 (Pb-Free)	3000 / Tape & Reel
PACDN042YB3R	SC70-3 (Pb-Free)	3000 / Tape & Reel
PACDN044YB5R	SC70-5 (Pb-Free)	3000 / Tape & Reel
PACDN045YB6R	SC70-6 (Pb-Free)	3000 / Tape & Reel
PACDN044TR	TSSOP8 (Pb-Free)	2500 / Tape & Reel
PACDN046MR	MSOP8 (Pb-Free)	4000 / Tape & Reel

[†] For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{2.} **DISCONTINUED:** These devices are not available. Please contact your **onsemi** representative for information. The most current information on these devices may be available on www.onsemi.com.

REVISION HISTORY

Revision	Description of Changes	Date
9	Rebranded the Data Sheet to onsemi format. PACDN044Y5R, PACDN045Y6R, PACDN043Y4R, PACDN042YB3R, PACDN044YB5R, PACDN045YB6R, PACDN044TR, PACDN046MR OPNs Marked as Discontinued.	09/10/2025

This document has undergone updates prior to the inclusion of this revision history table. The changes tracked here only reflect updates made on the noted approval dates.

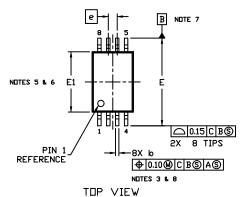
PACKAGE DIMENSIONS

NOTES:

TSSOP8, 4.4x3.0, 0.65P CASE 948AL **ISSUE A**

DATE 20 MAY 2022







NOTES 4 & 6 Α NOTE 7 // 0.05 C NOTE 9 △ 0.10 C SEATING PLANE 8X A2 SIDE VIEW



DETAIL A NOTE 8

END VIEW

MILLIMETERS MIN. NDM. DIM MAX. 1.20 Α 0.05 0.15 A1 Α2 0.80 0.90 1.05 0.19 0.30 b 0.09 ---0.20 D 2.90 3.00 3.10 Ε 6.30 6.40 6.50 E1 4.30 4.40 4.50 0.65 BSC e 1.00 REF L 0.50 0.60 0.70 L1 0. 8* θ

DIMENSIONING AND TOLERANCING PER ASME Y14.5, 2009.. CONTROLLING DIMENSION MILLIMETERS DIMENSION & DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL NOT BE 0.15 IN EXCESS OF MAXIMUM MATERIAL

PROTRUCTION SINCE NOT BE SHOULD AND ALL CONDITION.

DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.

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OLIO PER SIDE.

0.15 PER SIDE.
DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION.
INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 PER SIDE.
THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM.
DIMENSIONS D AND E1 ARE DETERMINED AT THE OUTERMOST EXTREMES OF
THE PLASTIC BODY AT DATUM PLANE H.
DIMENSIONS & AND B ARE TO BE DETERMINED AT DATUM H.
DIMENSIONS & AND B APE TO BE DETERMINED AT DATUM H.
DIMENSIONS & AND B APPLY TO THE FLAT SECTION OF THE LEAD
BETWEEN 0.10 AND 0.25 FROM THE LEAD TIP..
A1 IS DEFINED AS THE LOWEST VERTICAL DISTANCE FROM THE SEATING
PLANE TO THE LOWEST POINT ON THE PACKAGE BODY..

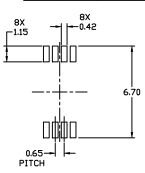
GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

= Year WW = Work Week Α = Assembly Location = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.



RECOMMENDED MOUNTING FOOTPRINT*

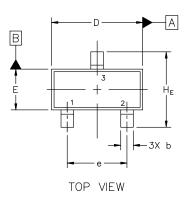
For additional information on our Pb-Free rur auditional information on our Pb-Free strategy and soldering details, please download the IIN Semiconductor Soldering and Mounting Techniques Reference Manual, SILDERRM/D.

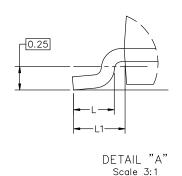


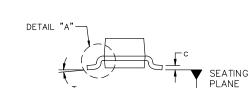


SOT-23 (TO-236) 2.90x1.30x1.00 1.90P **CASE 318 ISSUE AU**

DATE 14 AUG 2024







END VIEW



NOTES:

- DIMENSIONING AND TOLERANCING 1. PER ASME Y14.5M, 2018. CONTROLLING DIMENSIONS:
- MILLIMETERS.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE
- BASE MATERIAL.
 DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.



SIDE VIEW

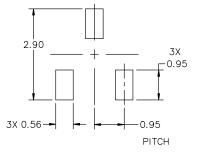


XXX = Specific Device Code

= Date Code

= Pb-Free Package

^{*}This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "=", may or may not be present. Some products may not follow the Generic Marking.



C

RECOMMENDED MOUNTING FOOTPRINT

* For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLES ON PAGE 2

DOCUMENT NUMBER:	98ASB42226B	Electronic versions are uncontrolled except when accessed directly from the Documen Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	SOT-23 (TO-236) 2.90x1.3	0x1.00 1.90P	PAGE 1 OF 2

SOT-23 (TO-236) 2.90x1.30x1.00 1.90P CASE 318 ISSUE AU

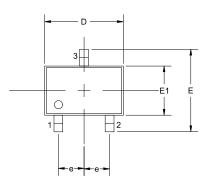
DATE 14 AUG 2024

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 7: PIN 1. EMITTER 2. BASE 3. COLLECTOR	STYLE 8: PIN 1. ANODE 2. NO CONNECTION 3. CATHODE	1	
STYLE 9:	STYLE 10:	STYLE 11:	STYLE 12: PIN 1. CATHODE 2. CATHODE 3. ANODE	STYLE 13:	STYLE 14:
PIN 1. ANODE	PIN 1. DRAIN	PIN 1. ANODE		PIN 1. SOURCE	PIN 1. CATHODE
2. ANODE	2. SOURCE	2. CATHODE		2. DRAIN	2. GATE
3. CATHODE	3. GATE	3. CATHODE-ANODE		3. GATE	3. ANODE
STYLE 15:	STYLE 16:	STYLE 17:	STYLE 18:	STYLE 19:	STYLE 20:
PIN 1. GATE	PIN 1. ANODE	PIN 1. NO CONNECTION	PIN 1. NO CONNECTION	N PIN 1. CATHODE	PIN 1. CATHODE
2. CATHODE	2. CATHODE	2. ANODE	2. CATHODE	2. ANODE	2. ANODE
3. ANODE	3. CATHODE	3. CATHODE	3. ANODE	3. CATHODE-ANODE	3. GATE
STYLE 21:	STYLE 22:	STYLE 23:	STYLE 24:	STYLE 25:	STYLE 26:
PIN 1. GATE	PIN 1. RETURN	PIN 1. ANODE	PIN 1. GATE	PIN 1. ANODE	PIN 1. CATHODE
2. SOURCE	2. OUTPUT	2. ANODE	2. DRAIN	2. CATHODE	2. ANODE
3. DRAIN	3. INPUT	3. CATHODE	3. SOURCE	3. GATE	3. NO CONNECTION
STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE				

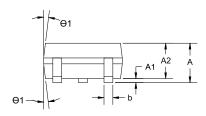
DOCUMENT NUMBER:	98ASB42226B	Electronic versions are uncontrolled except when accessed directly from the Document Repositor Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	SOT-23 (TO-236) 2.90x1.3	0x1.00 1.90P	PAGE 2 OF 2	



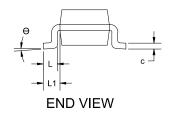




TOP VIEW



SIDE VIEW



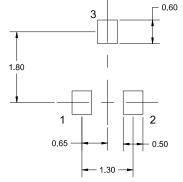
SC-70, 3 Lead, 1.25x2 CASE 419AB ISSUE A

DATE 13 FEB 2023

NOTES:

- 1. ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES IN DEGREES.
- 2. COMPLIES WITH JEDEC MO-203

	MILLIMETERS			
DIM	MIN.	NOM.	MAX.	
Α	0.80		1.10	
A1	0.00		0.10	
A2	0.80	0.90	1.00	
b	0.15		0.30	
С	0.08		0.22	
D	1.80	2.00	2.20	
E	1.80	2.10	2.40	
E1	1.15	1.25	1.35	
е		0.65 BSC		
L	0.26	0.36	0.46	
L1		0.42 REF		
θ	0°		8°	
0 1	4°		10°	



SOLDERING FOOTPRINT

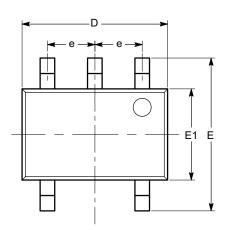
For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON34256E	Electronic versions are uncontrolled except when accessed directly from the Document Reposi Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	SC-70, 3 LEAD, 1.25X2		PAGE 1 OF 1

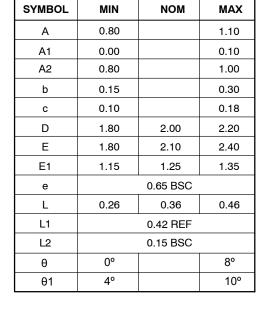


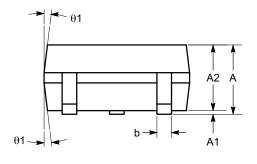
SC-88A (SC-70 5 Lead), 1.25x2 CASE 419AC-01 ISSUE A

DATE 29 JUN 2010

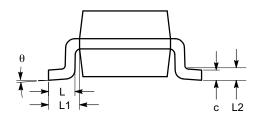


TOP VIEW





SIDE VIEW



END VIEW

Notes

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC MO-203.

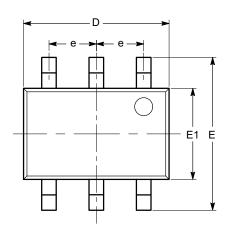
DOCUMENT NUMBER:	PRAON34260E Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	SC-88A (SC-70 5 LEAD), 1.25X2		PAGE 1 OF 1



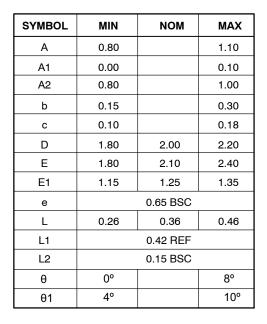


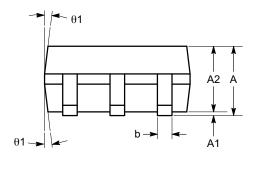
SC-88 (SC-70 6 Lead), 1.25x2 CASE 419AD ISSUE A

DATE 07 JUL 2010

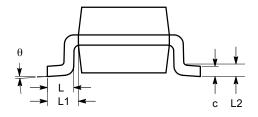


TOP VIEW





SIDE VIEW



END VIEW

Notes:

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC MO-203.

DOCUMENT NUMBER:	98AON34266E	Electronic versions are uncontrolled except when accessed directly from the Document Repositor Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	SC-88 (SC-70 6 LEAD), 1.25X2		PAGE 1 OF 1



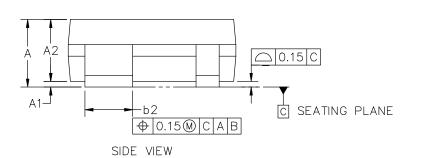




SOT-143, 4 LEAD, 2.90x1.30x0.90, 1.92P CASE 527AF **ISSUE B**

DATE 26 FEB 2024

4 3 2 ◆ 0.15 M C A B e1 -◆ 0.20 M C A B

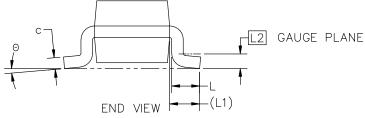


TOP VIEW

NOTES:

- DIMENSION AND TOLERANCING PER ASME Y14.5M, 2018
- 2. CONTROLLING DIMENSION: **MILLIMETERS**

SYMBOL	MIN	NOM	MAX
А	0.80	1.01	1.22
A1	0.05	0.10	0.15
A2	0.75	0.90	1.07
Ф	0.30	0.40	0.50
b2	0.76	0.83	0.89
С	0.08	0.14	0.20
D	2.80	2.90	3.04
E	2.10	2.37	2.64
E1	1.20	1.30	1.40
е	1.92 BSC		
e1		0.20 BSC	
L	0.40	0.50	0.60
L1	0.54 REF		
L2	0.25 BSC		
Θ	0°	_	8°



GENERIC MARKING DIAGRAM*



XXX = Specific Device Code = Month Code

= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	98AON34306E	Electronic versions are uncontrolled except when accessed directly from the Document Repositor Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	SOT-143, 4 LEAD, 2.90x1.30x0.90, 1.92P		PAGE 1 OF 1

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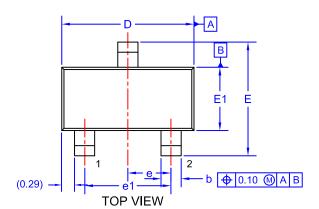






SOT-23/SUPERSOT™-23, 3 LEAD, 1.4x2.9 CASE 527AG **ISSUE A**

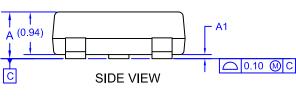
DATE 09 DEC 2019

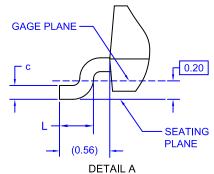


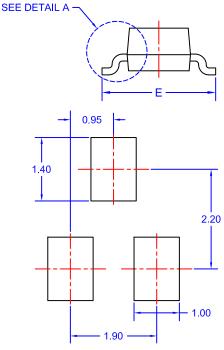
NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- DIMENSIONS ARE EXCLUSIVE OF BURRS,
 MOLD FLASH AND TIE BAR EXTRUSIONS.

DIM	MIN.	NOM.	MAX.
Α	0.85	0.95	1.12
A1	0.00	0.05	0.10
b	0.370	0.435	0.508
С	0.085	0.150	0.180
D	2.80	2.92	3.04
Е	2.31	2.51	2.71
E1	1.20	1.40	1.52
е	0.95 BSC		
e1	1.90 BSC		
L	0.33	0.38	0.43







LAND PATTERN RECOMMENDATION*

*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

GENERIC MARKING DIAGRAM*

XXXM=

XXX = Specific Device Code = Month Code

= Pb-Free Package

(Note: Microdot may be in either location)

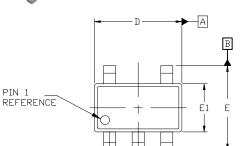
*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	98AON34319E	Electronic versions are uncontrolled except when accessed directly from the Document Repository Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	SOT-23/SUPERSOT-23, 3 LEAD, 1.4X2.9		PAGE 1 OF 1

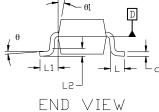
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TOP VIEW



GENERIC MARKING DIAGRAM*



XXX = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

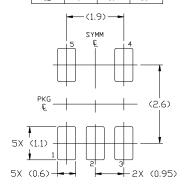
SOT-23, 5 Lead CASE 527AH ISSUE A

DATE 09 JUN 2021

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 19894
- CONTROLLING DIMENSION: MILLIMETERS
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS.
 MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
- 4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED O. 25 PER SIDE. D AND E1 DIMENSIONS ARE DETERMINED AT DATUM D.
- 5. DIMENSION '6' DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08mm TOTAL IN EXCESS OF THE '6' DIMENSION AT MAXIMUM MATERIAL CONDITION. MINIMUM SPACE BETWEEN PROTRUSION AND AN ADJACENT LEAD SHALL NOT BE LESS THAN 0.07mm.

	MILLIMETERS		
DIM	MIN.	N□M.	MAX.
Α	0.90	_	1.45
A1	0.00	_	0.15
A2	0.90	1.15	1.30
b	0.30	_	0.50
C	0.08	_	0.22
D	2.90 BSC		
Ε	2.80 BSC		
E1	1.60 BSC		
е	0	.95 BSC	
L	0.30	0.45	0.60
L1	0	.60 REF	
L2	0.25 REF		
θ	0°	4°	8°
θ1	0°	10°	15°
θ2	0°	10°	15°



RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDL DERRM/D.

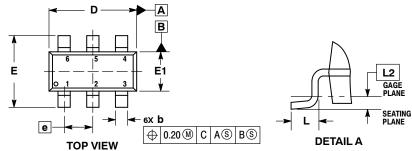
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DESCRIPTION:	SOT-23, 5 LEAD		PAGE 1 OF 1

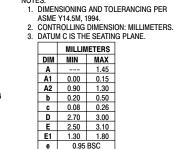


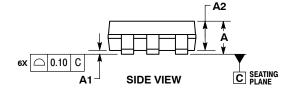
SCALE 2:1

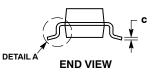


DATE 29 FEB 2012



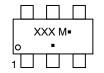






GENERIC MARKING DIAGRAM*

0.20 0.60



XXX = Specific Device Code

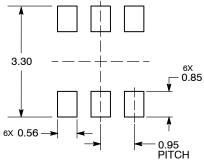
M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

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DESCRIPTION:	SOT-23, 6 LEAD		PAGE 1 OF 1

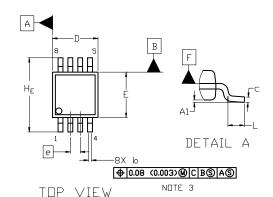
^{*}For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

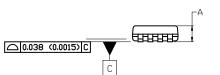




Micro8 CASE 846A-02 ISSUE K

DATE 16 JUL 2020



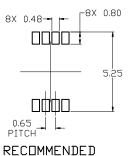




SIDE VIEW

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
- CONTROLLING DIMENSION: MILLIMETERS
- DIMENSION 6 DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.10 mm IN EXCESS OF MAXIMUM MATERIAL CONDITION.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 mm PER SIDE. DIMENSION E DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 mm PER SIDE. DIMENSIONS D AND E ARE DETERMINED AT DATUM F.
- DATUMS A AND B ARE TO BE DETERMINED AT DATUM F.
- A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.



MOUNTING FOOTPRINT

DIM	MI	LLIMETE	RS
MIM	MIN.	N□M.	MAX.
Α			1.10
A1	0.05	0.08	0.15
b	0.25	0.33	0.40
С	0.13	0.18	0.23
D	2.90	3.00	3.10
Е	2.90	3.00	3.10
е	0.65 BSC		
HE	4.75	4.90	5.05
L	0.40	0.55	0.70

8. N-DRAIN

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code Α = Assembly Location

Υ = Year W = Work Week = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

STYLE 1:	STYLE 2:	STYLE 3:
PIN 1. SOURCE	PIN 1. SOURCE 1	PIN 1. N-SOURCE
2. SOURCE	2. GATE 1	2. N-GATE
SOURCE	SOURCE 2	P-SOURCE
4. GATE	4. GATE 2	4. P-GATE
5. DRAIN	5. DRAIN 2	5. P-DRAIN
6. DRAIN	6. DRAIN 2	6. P-DRAIN
7. DRAIN	7. DRAIN 1	7. N-DRAIN

8. DRAIN 1

DOCUMENT NUMBER:	98ASB14087C	Electronic versions are uncontrolled except when accessed directly from the Document Repositor Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	MICRO8		PAGE 1 OF 1

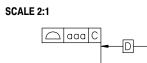


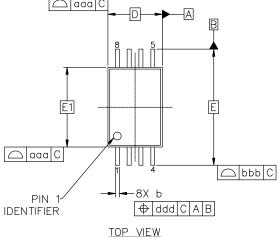


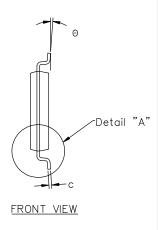
TSSOP-8 3.00x4.00x0.90, 0.65P

CASE 948S ISSUE D

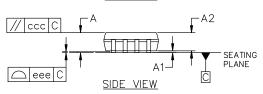
DATE 24 OCT 2025







MILLIMETERS DIM MIN NOM MAX0.90 1.10 Α 1.00 A1 0.05 0.10 0.15 Α2 0.80 0.90 1.00 b 0.19 0.25 0.30 0.09 0.15 0.20 C D 3.00 BSC Ε 6.40 BSC E1 4.40 BSC 0.50 0.60 0.70 L1 1.00 REF L2 0.25 BSC Θ 0. 4° 8. TOLERANCE FORM & POSITION 0.10 aaa bbb 0.20 0.10 ccc 0.10 ddd 0.05 eee



NOTES

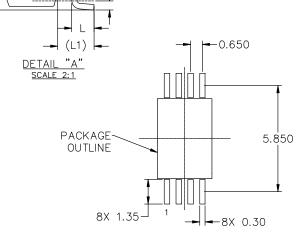
- DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M, 2018.
- CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSION "D" DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR
 GATE BURRS. MOLD FLASH, PROTRUSION OR GATE BURRS SHALL
- NOT EXCEED 0.15 PER SIDE.

 DIMENSION "E1" DOES NOT INCLUDE INTERLEAD FLASH OR

 PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT
- EXCEED 0.25 PER SIDE.

 DIMENSION "b" DOES NOT INCLUDE DAMBAR PROTRUSION.

 ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08mm TOTAL IN EXCESS OF THE "b" DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD IS 0.07mm.



L2 GAUGE PLANE

GENERIC MARKING DIAGRAM*

XXX YWW A •

XXX = Specific Device Code = Assembly Location

= Year

ww = Work Week = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "=", may or may not be present. Some products may not follow the Generic Marking.

RECOMMENDED MOUNTING FOOTPRINT

*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	TSSOP-8 3.00x4.00x0.90, 0.65P		PAGE 1 OF 1

SEATING PLANE

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